

Model	No.:
Date /	Rev

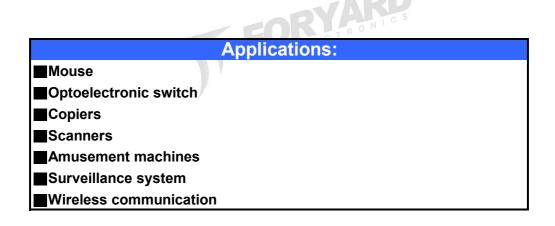
FYLS-1206PDB 2020.10.31 / A

PRODUCT SPECIFICATION

Model No.: FYLS-1206PDB

	F	eat	ure	s:
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- SMD Type Size (mm):3.20*1.60*1.10
- Emitting Color: Photo diode
- Lens Color: Black.
- SMT package
- Suitable for all SMT assembly and soldering method
- ■Pb-free Reflow soldering application
- RoHS Compliant
- MSL:4





CUSTOMER APPROVED SIGNATURES	APPROVED BY	CHECKED BY	PREPARED BY

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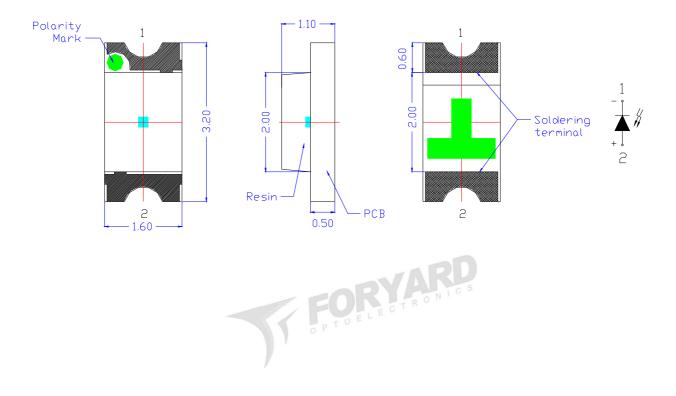
 E-mail:Sales@foryard.com (General)
 (General)

Http://www.foryard.com

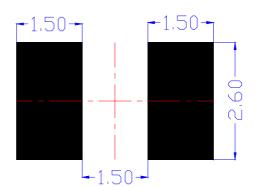


Model No.;	FYLS-1206PDB
Date / Rev.	2020.10.31 / A

Mechanical Dimensions



Recommend Soldering pad design(unit=mm)



Notes:

1. Dimension in millimeter, tolerance is ± 0.10 .

2.Angle:±5°

3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

4. The drawing is different from the actual one, please refer to the sample.

Http://www.forvard.com



Model No.:	FYLS-1206PDB
Date / Rev.	2020.10.31 / A

■ Absolute Maximun Ratings(Ta=25°C)

Parameter	Symbol	Ratings	Unit	
Power Dissipation (or below) 25 Free Air Temperature	PD	150	mW	
Reverse Voltage	V _R	32	V	
Operating Temperature Range	Topr	-25~ +85	°C	
Storage Temperature Range	Tstg	-40~ +100	°C	
Soldering Tomperature	Tsol	Reflow soldering : 260°C, 5s		
Soldering Temperature	ISOI	Hand soldering	:300°C, 3s	

■ Typical Electrical &Optical Charcteristics(Ta=25°C)

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Open-Circuit Voltage	VOC	Ee=5mW/cm ² λp=940nm		0.3		v
Short- Circuit Current	ISC	Ee=1mW/cm ² λp=940nm		6.5		μA
Reverse Light Current	IL	Ee=1mW/cm ² λp =875nm V _R =5V	4	7		μA
Reverse Light Current	E	Ee=1mW/cm ² λp =940nm V _R =5V	S	7		μA
Reverse Dark Current	ID OP T	Ee=0mW/cm ² V _R =5V			20	nA
Reverse Breakdown Voltage	BVR	Ee=0mW/cm ² I _R =100 μa	33	170		V
Forward Voltage	VF	I _F =20mA	0.5		1.3	V
Rise Time	t _r	V _R =10V R _L =1000Ω		50		nS
Fall Time	t _f	V _R =10V R _L =1000Ω		50		nS
Total Capacitance	Ct	Ee=0mW/cm ² V _R =3V f=1MHZ		505		pF
Rang Of Spectral Bandwidth	λ _{0.5}		420		1100	nm
Wavelength of Peak Sensitivity	λр			940		nm
View Angle	201⁄2	V _R =5V		120		Deg

Material

Item	Reflector	Wire	Encapsulate	Chip
Material	/	Gold	Ероху	AlGaAs/Si

Note:

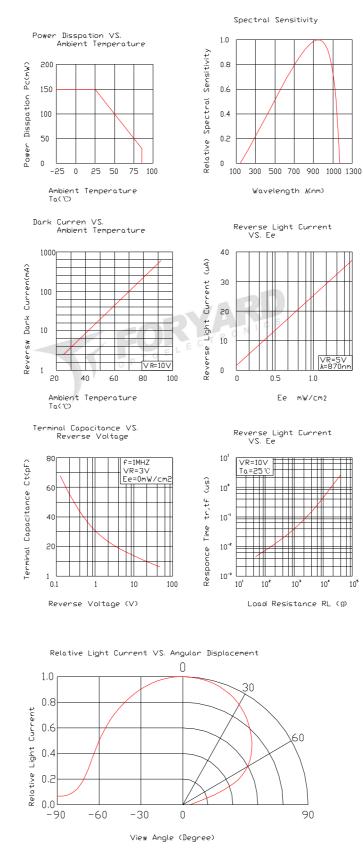
1.Luminous Intensity is based on the Foryard standards.

2.Pay attention about static for InGaN



Model No.:	FYLS-1206PDB
Date / Rev.	2020.10.31 / A

Electrical-Optical Characteristics-



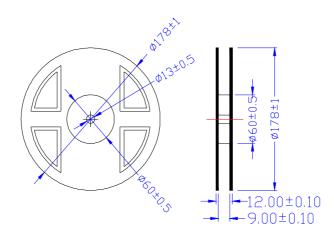




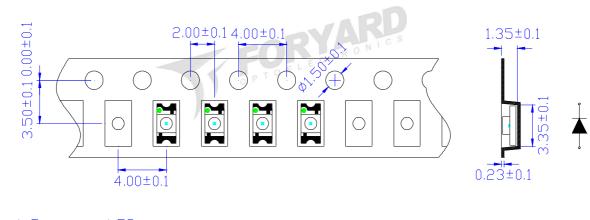
Model No.:	FYLS-1206PDB
Date / Rev.	2020.10.31 / A

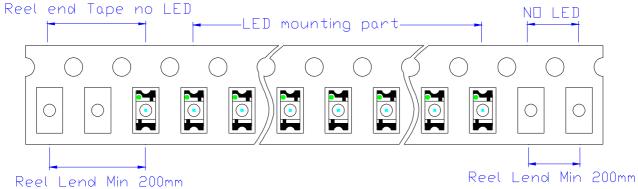
Package-

1. Reel Dimension



2. Tape Dimension





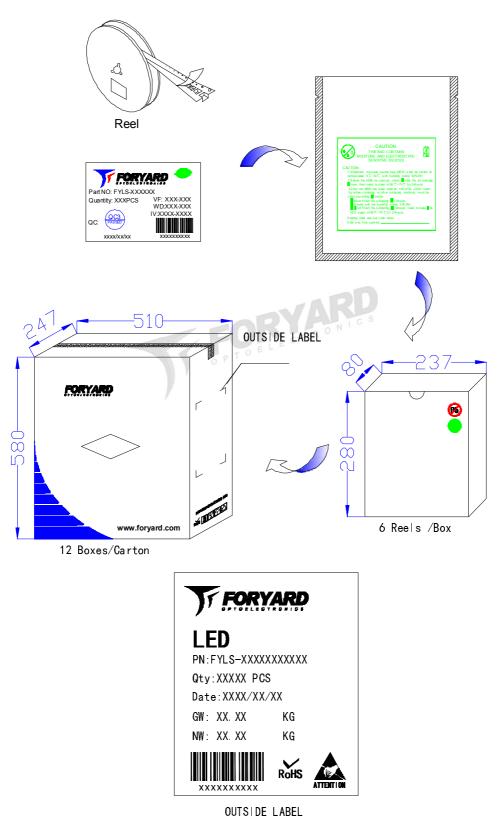
Notice:

1.Tolerance unless mentioned is $\pm 0.2 \text{mm}$



Model No.:	FYLS-1206PDB
Date / Rev.	2020.10.31 / A

3.Packing Diagram



Notice:

1.Quantity:3000 PCS/Reel

2. The specifications are subject to change without notice. Please contact us for updated information.

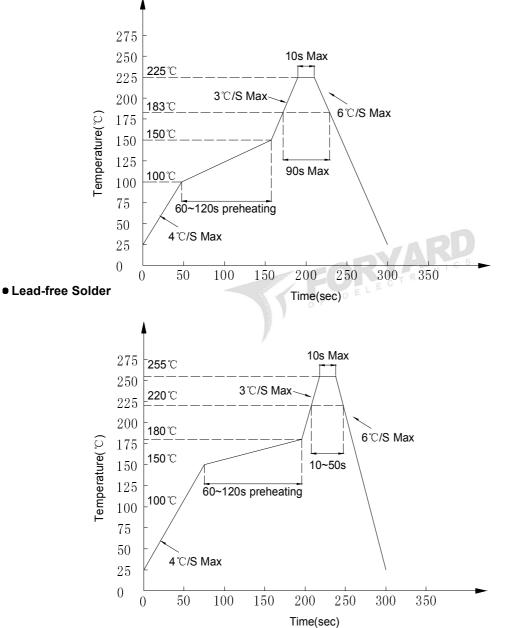


Model No.:	FYLS-1206PDB
Date / Rev.	2020.10.31 / A

Soldering Characteristics-

Reflow Soldering

Lead Solder



Notes:

1.Although the recommended soldering conditions are specified in above table, reflow or hand soldering at the lowest possible temperature is desired for the LEDs.

2.A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.

3.All temperatures refer to solder Pad.

Hand Soldering

Soldering temperature	300℃ Max. (25W Max.)	One time olny
Soldering time	3 ±1sec	



Model No.;	FYLS-1206PDB	
Date / Rev.	2020.10.31 / A	

Handling of Silicone Resin LEDs-

Handling Indications

When handling the product, do not touch it directly with bare hands as it may contaminate the surface and affect on optic characteristics. In the worst cases, excessive force to the product might result in catastrophic failure due to package damage and/or wire breakage.



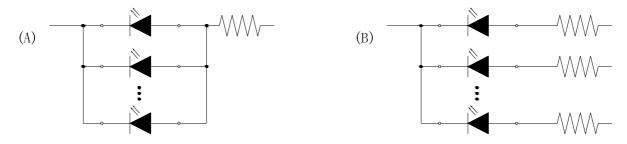
When handling the product with tweezers,LEDs should only be handled from the side and make sure that excessive force is not applied to the resin portion of the pordct. Failure to comply can cause the resin portion of the product to be cut,chipped,delaminated and/or deformed, and wire to be broken, and thus resulting in catastrophic failure.





Recommended circuit-

• In designing a circuit, the current through each LED must not exceed the absolute maximum rating specified for each LE It is recommended to use Circuit B which regulates the current flowing through each LED. In the meanwhile, when driving L with a constant voltage in Circuit A, the current through the LEDs may vary due to the variation in forward voltage(VF) of the LEDs. In the worst case, some LED may be subjected to stresses in excess of the absolute maximum rating.



• This product should be operated in forward bias. A driving circuit must be designed so that the product is not subjected to either forward or reverse voltage while it is off. In particular, if a reverse voltage is continuously applied to the product; such operation can cause migration resulting in LED damage.

Storage-

Storage Conditions

1.Unopened moisture barrier bag (MBB) shall be stored at temperature below $5^{\circ}C \sim 30^{\circ}C$, with humidity below $60^{\circ}RH$. 2.Before the MBB be opened, check if have the air leakage, if have, then need to bake at $65^{\circ}C \sim 70^{\circ}C$ for 24hours.

- 3.After the MBB has been opened, the LEDs which need for reflow soldering or other soldering methods, must be used according to below:
 - a: Must finish the soldering in 72hours
 - b: Stored with the humidity below 30%RH
 - c: If not finish the soldering in 72hours, need to bake the LED again at 65° C ~70 °C for 24hours